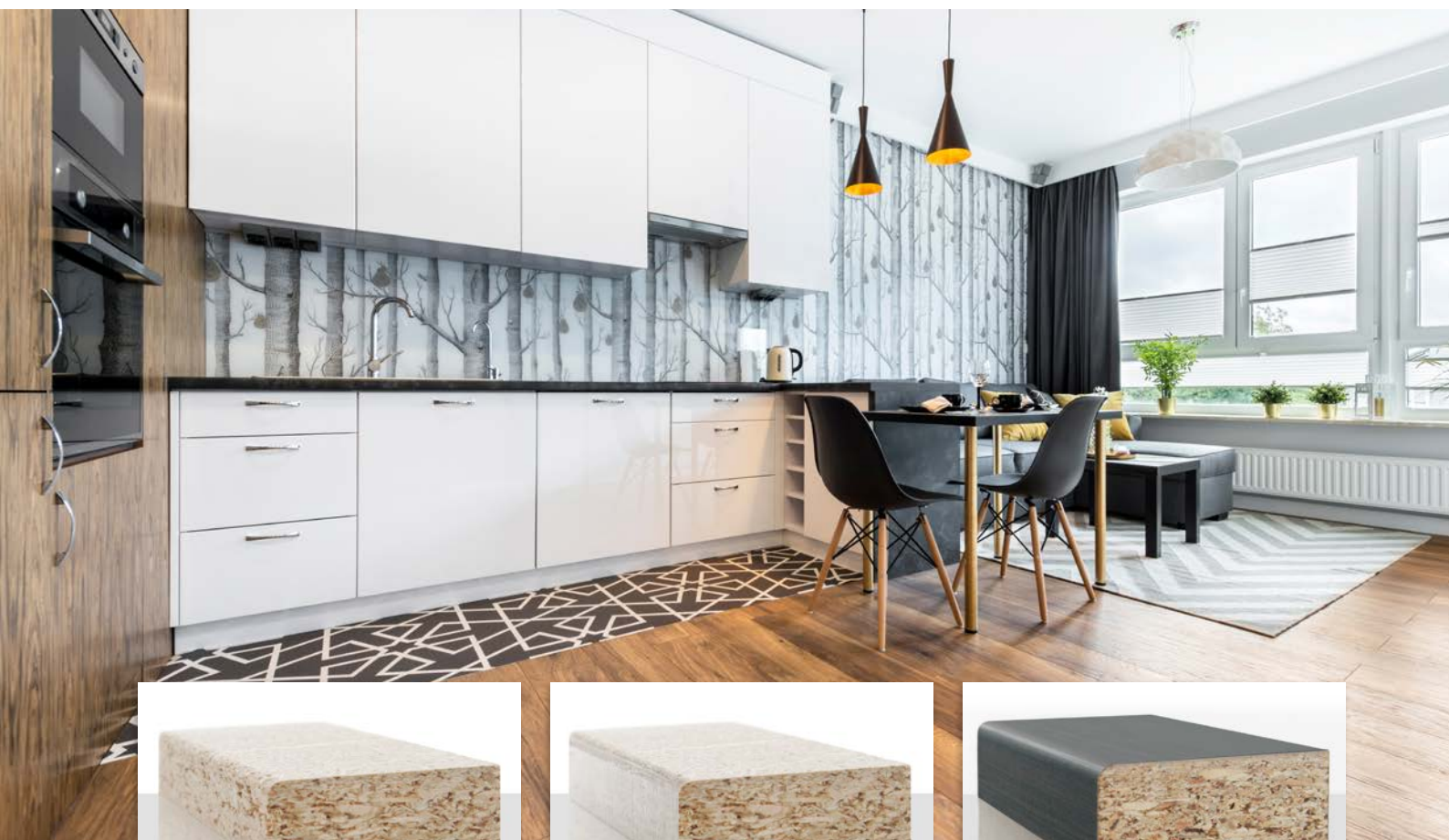


Lamination with integrated sealing/wrapping **Complete Line**



1. Highly porous middle layer of chipboard prevents wrapping with thin paper foils.



2. The sealing compound KLEIBERIT 762.3 or KLEIBERIT 755.0 guarantees excellent filling of the middle layer.



3. The finished product:
Edge and surface look exactly the same

For a long time the demand of the furniture and interior fittings industry has been for products for the effective sealing of chipboard edges. Through filling of the porous middle layer, profiled chipboards can also be wrapped with very thin paper foils, without the danger of telegraphing. The use of more homogenous but significantly more expensive materials, such as MDF, can therefore be avoided.

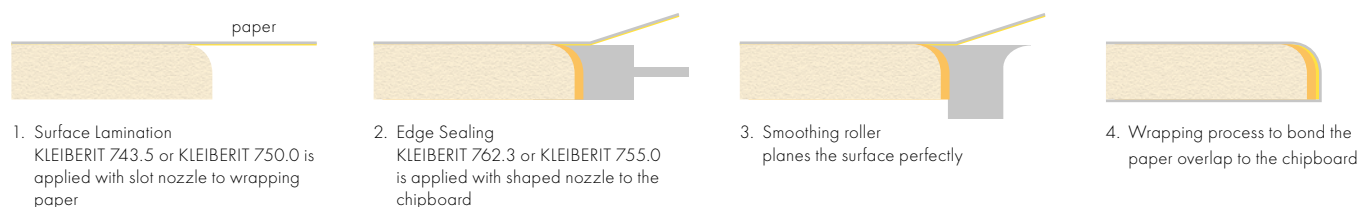
Lamination with integrated edge sealing/wrapping

Edge sealing / Edge banding

FRIZ Kaschiertechnik, Weinsberg Germany, has developed a process together with KLEIBERIT in which the sealing of chipboard edges is integrated with the surface bonding and wrapping with thin paper.

Hotmelt adhesive is applied with a slot nozzle to the edge of the chipboard cross section for:

1. a very smooth surface
2. the use of paper foils for edge wrapping (edge banding)



Complete Line adhesive system for normal temperature resistance

Edge Sealing with KLEIBERIT 762.3, EVA base

Surface Lamination/Edge Wrapping with KLEIBERIT 742.3/743.5, EVA base

- exceptional application properties
- line speeds up to 60 m/min
- high initial strength
- excellent temperature resistance

Complete Line adhesive system for high temperature resistance

Edge Sealing with KLEIBERIT 755.0, PO base

Surface Lamination/Edge Wrapping with KLEIBERIT 750.0, PO base

- perfect compatibility
- line speeds 60 m/min and more
- very high initial strength
- outstanding high temperature resistance (especially for export markets)

Surface Lamination/Edge Wrapping with KLEIBERIT 702.1, PUR base

- very high initial strength as well as pronounced stickiness
- line speeds 20-50 m/min

Overview of adhesive for surface lamination

Product	Base	Viscosity 180 °C [mPa·s]	Application temperature	Characteristics/Applications
702.1	PUR	12.000 at 120 °C	120 - 130 °C	Wrapping wood based materials with PVC foils and thin papers for interior use
742.3	EVA	10.000	180 - 200 °C	Lamination of paper foils on wood and wood based materials such as chipboard and MDF panels
743.5	EVA	8.000	180 - 200 °C	Hotmelt for the surface lamination of wood based materials with thin paper foils.
750.0	PO	22.000	180 - 200 °C	
755.0	PO	29.000	180 - 200 °C	Sealing compound for the sealing of chipboard in preparation for the direct wrapping with décor paper foils. Excellent filling of the middle layer, very smooth surface, very high temperature resistance, excellent melting properties
762.3	EVA	15.000	180 - 200 °C	